

Automotive Reflow Connectors

Automotive | Auto Electronics & Electricals | E-Components

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Benefits

- Reliable
- High temperature resistant
- High melting point
- Cost effective
- High co-planarity
- Low warpage after soldering
- High mechanical performance
- High flowability enables thin wall designs



Details

ForTii® PA4T is a reliable choice for applications such as automotive reflow connectors due to its high temperature resistance and melting temperature of 325° C. It is a cost-effective solution because of its high mechanical performance after reflow soldering and high dimensional stability. Offering low isotropic CTE leading to a high co-planarity and low warpage after soldering, ForTii® PA4T's high mechanical performance leads to reduced reject rates during pin assembly, while its high flowability enables thinner wall designs.

Products

ForTii® F11
PPA-GF30 FR(40)

ForTii® T11
PPA-GF30 FR(40)

ForTii® JTX2
PPA-GF30

ForTii® TX1
PPA-GF30 FR(40)

ForTii® Ace JTX8
PPA-GF30



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